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IC PACKAGING MATERIALS

2009 EDITION

A Strategic Report on the Diverse Markets for IC Packaging Materials

Report Coverage

- Wire Bonding
- Leadframes
- Substrates
- Solder Balls
- Underfill
- Molding/Encapsulation

Report Highlights

- Technology Updates
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- Industry Outlook Unit
- and Revenue Forecasts 2009–2013

New Venture Research *A Technology Market Research Company*

337 Clay St., Suite 101
Nevada City, CA 95959
Tel: (408) 244-1100 Fax: (408) 864-2138

Info@newventureresearch.com
www.newventureresearch.com

IC Packaging Materials, 2009 Edition

Synopsis

Although IC shipments have dropped significantly in 2009, this is merely a dip in the road. Volumes have already begun to move upward again, and customers will require an ever-increasing portfolio of IC packaging materials to meet the unique needs of various products.

In its report, **IC Packaging Materials, 2009 Edition**, *New Venture Research* uses information from IC packaging industry insiders to present the most realistic forecasts available regarding the IC packaging materials markets. This report covers all the critical materials found in IC packaging, as well as the newest IC packaging materials and lat- est research from many organizations.

Chapter 1 explains the scope and methodology of the report; Chapter 2 summarizes the IC packaging material revenue.

Chapter 3 presents NVR's views on the state of the semiconductor industry. This includes NVR's base semiconductor forecast (see Figure 1) and a review of the industry's third-quarter results.

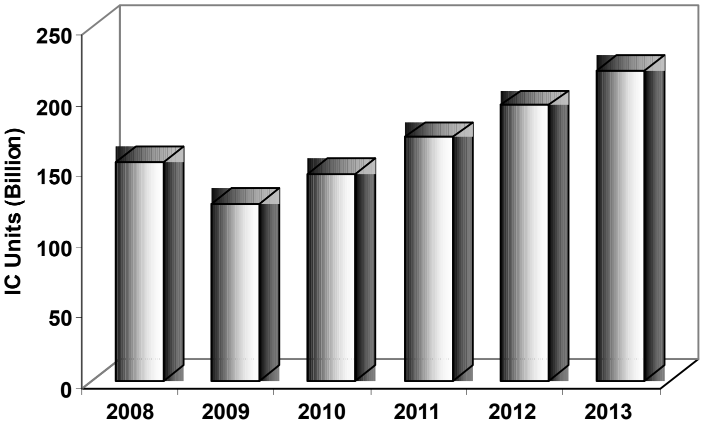

Figure 1 IC Unit Forecast

Chapter 4 presents the **wire bonding** market—including wire bonding methods, product highlights, and forecasts of bonding wire materials, wire thicknesses, and wire revenue.

Chapter 5 details the **leadframe** market. This chapter presents product highlights and leadframe unit and revenue forecasts by I/O count, pitch, and plating finish.

Chapter 6 presents the **substrate** market, including an overview of substrate types and materials, and highlights of recent developments in substrates. Forecasts are provided for substrate units, area, and revenue by package type and substrate material.

Chapter 7 gives an overview of the **solder sphere** market, with product highlights and forecasts of solder sphere units, price, and revenue by package family, material, and size.

Chapter 8 reviews the **underfill** market, with product highlights and volume and revenue fore- casts for the various types of underfill.

Chapter 9 covers the **molding/encapsulation** market, including product highlights and forecasts for the halogen-free transition and overall mold compound revenue.

As the future of the IC packaging materials is critical to your business, please review the report's outline on the following pages. **IC Packaging Materials, 2009 Edition** will provide you with the critical information you need to assess this market. The report is available in electronic format only and is delivered by email as a single-user PDF file. The report sells for $1995, with extra single-user licenses at $250 each. Corporate licensing is available—contact us for pricing.

About the Author

Sandra Winkler is the senior analyst for IC packaging at New Venture Research (NVR). She began her analyst career as an independent consultant to the telecommunications industry over 20 years ago. Since 1995, Ms. Winkler has authored all of NVR's widely cited reports on IC packaging. She has spoken at numerous industry conferences and is a contributing editor for Chip Scale Review magazine. Ms. Winkler has an MBA from Santa Clara University. She is currently serving as Program Co-Chair for the Silicon Valley Chapter of the IEEE-CPMT.

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